

## Call for Application to Interested MD Companies

## **SmartMFG+ Incentive Programme**

(Scale-up Tech Solution Provider Project)

Supporting the New Industrial Master Plan (NIMP 2030)



# Content of this Programme Kit

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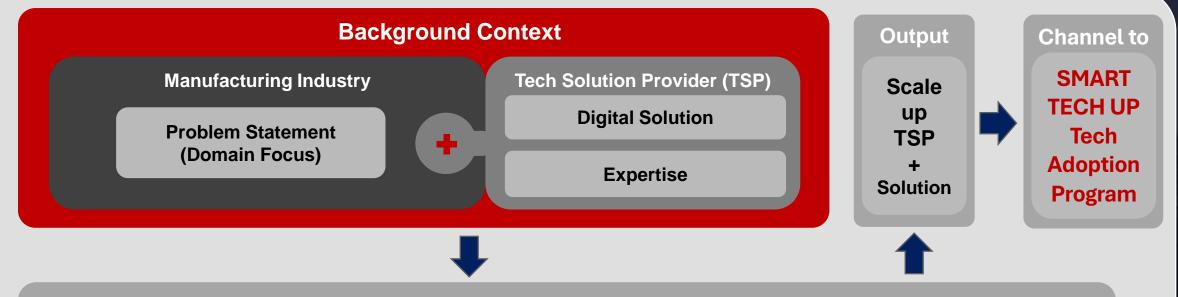
(1) Overview of the Incentive Programme

### **SmartMFG+**

**Incentive Programme** 

This incentive programme supports selected <u>local Malaysia Digital</u> (MD) companies in scaling-up digital solutions for the <u>manufacturing</u> <u>sector</u> in-line with the New Industrial Master Plan 2030 (NIMP) 2030 target to transform 3,000 smart factories by 2030.





Selected TSPs will undergo and benefit from the following initiatives under this programme

**1. Solution Development** (Financial Incentive)

**4. Use Cases Report Document** (Publicity)

2. Physical Testbed / Sandbox (Validation/Testing)

- **5. Solution Showcase Event** (Business Dev)
- 3. Capacity Building (Technical Track & Management/Commercial Track)

## **SmartMFG+**

**Incentive Programme** 

Interested Tech Solution Provider (TSP) applying needs to:



Commit to undergo all the sessions and deliverables under this programme\*

### **Overall Project Timeline (2025) subject to change**

| Scope                             | June | July                 | August              | Sept                     | Oct                                    | Nov | Dec                     |
|-----------------------------------|------|----------------------|---------------------|--------------------------|--|-----|-------------------------|
| 1. TSP Selection                  |      | Selection<br>process |                     | nboarded<br>ing / Launch |  |     |                         |
| 2. Capacity Building              |      |                      | Innovatio<br>Review |                          | e Immersion and<br>y Building Sessions |     | Certificate<br>Issuance |
| 3. Solution / Feature Development |      |                      |                     | Sc                       | olution Developme                      | nt  |                         |
| 4. Testbed / Sandbox              |      |                      |                     |                          |  |     | ion / Use<br>Testing    |
| 5. Commercialisation              |      |                      |                     |                          |  |     | Showcase<br>Event       |

<sup>\*</sup>Note: The sessions are expected to be conducted around Klang Valley



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**Incentive Programme** 

# Focus Domains on Empowering Digital Solutions for the Manufacturing Sector

Operational Efficiency & Production Optimization

Quality Control & Process Assurance

Supply Chain & Inventory Intelligence

Real-Time Production Intelligence Predictive
Maintenance &
Equipment Health



E.g. Automated Scheduling Tools, Lean Manufacturing Software, Manufacturing Execution Systems (MES)



E.g. Al-Based Visual Inspection, Statistical Process Control (SPC) Software, IoT-Based QA Monitoring



E.g. Demand Forecasting AI, RFID Tracking, Blockchain for Traceability



E.g. Live OEE
Dashboards, Edge
Analytics, AI-Powered
Anomaly Detection



E.g. Vibration Sensors, Al Failure Prediction Models, Digital Maintenance Logs

Example: Tech Solution Provider (TSP) plan to expand its existing digital solution by developing an AI-powered feature to automatically plan factory tasks by checking machine use, worker shifts, and urgent orders.



(2) Key Components of the Programme



**Incentive Programme** 

# Solution Development for the Manufacturing Industry



### Whats the ask from TSP?

To develop digital solution / feature / Minimum Viable Product (MVP) aligned with focus domain (page 6)

### **Given Timeline:**

3 Months (Expected around Aug until around Nov 2025)

### **Support Given to TSP:**



Funding Incentive Up to 70% of Solution development cost or up to RM75,000 (whichever is lower)



Network of **Subject Matter Expert** That Can Be Accessed

Innovation Review\*
\*at least with panel selected by MDEC

Submission of system architecture + UI/UX mockups

**Development Work** 

Submission of completed solution for review



|                       | Preparation  | Month 1  | Month 2  | Month 3   |
|-----------------------|--|--|--|---|
| Expected<br>Milestone | Alpha Development  (Adapting ICT and Technology Solutions to the | Beta Development  (Development of Application Core and | Prototype Development  (Matching Solutions to Manufacturing Industry | MVP Development (Solution Alignment to Manufacturing Industry |
|                       | Needs of the Manufacturing Industry)                             | UI/UX)   | Systems)   | Systems)  |



**Incentive Programme** 



## **Eligible Expenditure**

The Incentive (page 8) is intended to cover expenses related to the creation/development of the Solution, which shall be reviewed by the Selection Panel and specified in the agreement between MDEC and TSP:



Manpower cost for digitally skilled professionals related to the development, design and project management



Cost of IT Hardware and or IT equipment



Cost of setup/installation of hardware



Cost of Software



License fee / subscription fee for servers, cloud services and networking



Testing and certification costs

Any other eligible expenses directly related to the Solution development, is subject to approval by MDEC.

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# Validation / Review of the Developed Digital Solutions



#### Whats the ask from TSP?

Reviewing the completeness and performance of the digital solution / feature developed by each selected TSP

### **Given Timeline:**

Around 1 Month (Expected around end of Nov 2025)

### **Support Given to TSP:**



Access to a physical testbed / sandbox simulating the manufacturing environment



Technical expertise to conduct the review

|                       | End of Nov 2025                  |
|-----------------------|----------------------------------|
| Expected<br>Milestone | Solution<br>Validation<br>Report |



MDEC to compile the Solution Validation / Use Case Report as local digital solutions that are ready to support the New Industrial Master Plan (NIMP2030) goals



**Incentive Programme** 

# Capacity Building (3 pax from each TSP)



#### Whats the ask from TSP?

Each selected TSPs to nominate key person / potential successor within the company to undergo capacity building and peer-to-peer networking (e.g. sharing of best practices, industry insights)



### **Technical Track**

(2 pax from each TSP)

Within a <u>maximum of 10 days</u> (targeted between Aug - Nov 2025)



### **Management/Commercial Track**

(1 pax from each TSP)

Within a <u>maximum of 5 days</u> (targeted between Aug - Nov 2025)



**Incentive Programme** 





#### Whats the ask from TSP?

- Consent to be published in NIMP2030 related materials
- Commitment to participate in event (s) supporting the NIMP2030 goals
- TSPs are encouraged to offer free trials / POC for at least 5 potential clients attending the showcase

|                       | Targeted Dec 2025  |
|-----------------------|--|
| Expected<br>Milestone | Participation by all TSPs in the Digital Solutions for the Manufacturing Sector Showcase Event |

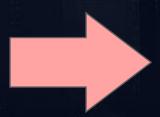
### **Support Given to TSP:**



Complimentary booth during the showcase event



Networking opportunities



Highlights on how the developed digital solutions are supporting the NIMP2030 goals

Note: TSPs to also provide information on their contribution to NIMP2030 goals from time to time including post programme



(3) Applying to join the programme

## **Eligibility Criteria**



| No. | Eligibility Criteria   |
|-----|--|
| 1   | <ul> <li>The TSP must be a company:</li> <li>i. Incorporated in Malaysia under Companies Act 1965 or the Companies Act 2016;</li> <li>ii. Has a minimum paid up capital of RM50,000.00;</li> <li>iii. Active and minimum of 51% shares held by Malaysian(s) individuals or companies owned by Malaysians with at least 51% shareholding; and</li> <li>iv. TSP must be an MSC Malaysia or Malaysia Digital (MD) status company.</li> </ul>  |
| 2   | In operation for at least one (1) year as at the date of submission of the application.  |
| 3   | Not the subject of liquidation/winding up/dissolution order and has no going concern issue.  |
| 4   | Directors/shareholders of TSP to declare and disclose if there is any business relationship / family relationship with any of MDEC's director, Employee or Individual Consultant engaged by MDEC.  • In the event where the said MDEC's director/Employee/Individual Consultant has any conflict of interest or perceived conflict of interest, the said MDEC's director/Employee/Individual Consultant shall declare its interest and abstain or withdraw itself (whichever is applicable based on the absolute and sole discretion of MDEC) from the deliberation, approval or voting process relating to the Project.  • For avoidance of doubt, family relationship means spouse, parent, grandparent, child, including adopted child and stepchild, grandchild, brother, sister, son-in-law, daughter-in-law, brother-in-law, sister-in-law, uncle, aunt, cousin. |
| 5   | TSP is not blacklisted in MDEC Blacklist Register and by any enforcement bodies/ authorities including but not limited to Malaysian Anti-Corruption Commission (MACC), Security Commission Malaysia (SC), Bank Negara Malaysia (BNM) and Companies Commission of Malaysia (SSM)  |
| 6   | TSPs with common shareholder(s) is only allowed to submit a single application for participation in this Project (this requirement is not applicable to venture capital investors and registered market operator e.g.: Equity Crowdfunding Platforms).   |
| 7   | Not a recipient of any grant/ funding / incentive program administered by MDEC, at the time of application.  |

## **Application Documents**



| No  | Application Documents Required  |
|-----|---|
| 140 |   |
| 1   | Fully completed application form (Online).  |
| 2   | Solution Proposal Deck/Document using MDEC template.  |
| 3   | MYDATA-SSM (Business or Company Profile), to be obtained from <a href="https://www.mydata-ssm.com.my/homePage">https://www.mydata-ssm.com.my/homePage</a> Note: Any search report should be dated less than 6 months prior to the date of application to MDEC.  |
| 4   | Company's financial statements (copies of one (1) year latest audited account).   |
| 5   | Copy of award(s) and/or recognition(s) received in the past 5 years (if any)  |
| 6   | Company Profile   |
| 7   | Signed copy of Appendix C of MDEC Integrity Pact Version 2.0  |
| 8   | MSC Malaysia or Malaysia Digital (MD) status approval letter  |
|     |   |
| No  | Additional Document Required If Shortlisted   |
| 1   | Liquidation/winding up/dissolution search result, to be obtained from <a href="https://e-insolvensi.mdi.gov.my/">https://e-insolvensi.mdi.gov.my/</a> Note: Any search report should be dated less than 6 months prior to the date of application to MDEC   |
| 2   | If TSP has previously received any grant/funding/incentive from MDEC and/or any other ministries or agencies under the Government of Malaysia, to provide proof of project completion (i.e: closure letter from the ministries/agencies). *Limited to 5 years records from the approval of the respective grant/funding/incentive |
| 3   | Certification/Evidence of compliance with any relevant industry standards e.g. ISO27001   |



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## **Submit Your Application Here!**



http://bit.ly/3STPfjG

